
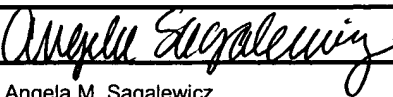


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	Application Number	10/802,378
	Filing Date	03/17/2004
	First Named Inventor	David T. Krick
	Art Unit	3749
	Examiner Name	Joyce, Harold
Total Number of Pages in This Submission		5
Attorney Docket Number		111548-136408

ENCLOSURES (Check all that apply)		
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SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT

Firm Name	SCHWABE, WILLIAMSON & WYATT, P.C.		
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Printed name	Angela M. Sagalewicz		
Date	12/27/2005	Reg. No.	56,113

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE BOARD OF PATENT APPEALS AND INTERFERENCES

In re Application for:

KRICK, DAVID T., ET AL

Application No.: 10/802,378

Assignee: Intel Corporation

Filed: March 17, 2004

For: AIR GRATE

Examiner: Joyce, Harold

Art Group: 3749

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MAIL STOP APPEAL BRIEF-PATENTS

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

APPELLANT'S APPEAL BRIEF:
REVISION PER NOTIFICATION OF NON-COMPLIANT APPEAL BRIEF

TO THE HONORABLE COMMISSIONER FOR PATENTS:

This paper is filed in response to the Notification of Non-Compliant Appeal Brief ("Notification") mailed November 30, 2005, for appellant's failure to provide a summary of the claimed subject matter as required by 37 C.F.R. §41.37(c)(1)(v). As provided by MPEP §1205.03(B), an appropriate correction for this type of non-compliance is submission of a compliant summary of the claimed subject matter rather than submission of an entire new brief. As such, appellant submits this corrected summary of the claimed subject matter.

V. SUMMARY OF THE CLAIMED SUBJECT MATTER

Various embodiments of the present invention relate to an air grate suitable for use to cover a fab-level air flow opening. For an embodiment, air grate **100** may comprise one or more pieces of one or more materials adapted to partially cover no more than 40% of a spanned area, allowing air to flow through a plurality of openings **102** disposed in the uncovered portion of the spanned area to meet a semiconductor device manufacturing air flow requirement, where each of the openings **102** is sufficiently small to meet a semiconductor device manufacturing fall through object size limitation, and where the one or more materials are further adapted to meet a semiconductor device manufacturing spill protection requirement. *See* page 4, paragraphs 13-17; page 5, paragraphs 19-20, with reference to figure 2; page 5, paragraph 21, with reference to figures 1a-1c. In alternate embodiments, the one or more pieces of one or more materials may be further adapted to cover the perimeter of the spanned area with an inwardly inclined edge **106** to meet the semiconductor device manufacturing spill protection requirement. *See id* and page 6, paragraph 28, with reference to figure 1b.

Still further, in other embodiments, air grate **100** may comprise one or more pieces of one or more materials adapted to partially cover no more than 40% of a spanned area, allowing air to flow through a plurality of openings **102** disposed in the uncovered portion of the spanned area to meet a semiconductor device manufacturing air flow requirement, where the one or more materials have a thickness less than 1.0 inch and a tensile strength to meet a semiconductor device manufacturing weight drop requirement of 300 lbs from a height of 2 feet, and where the one or more materials are further adapted to meet a semiconductor device manufacturing spill protection requirement. *See* pages 4-5, paragraphs 13-18; page 5, paragraphs 19-20, with reference to figure 2; and page 6, paragraph 25, with reference to figures 1a-1c. In various ones of these embodiments, the one or more pieces of one or more materials are further adapted to cover the perimeter of the spanned area with an inwardly inclined edge **106** to meet the semiconductor device manufacturing spill protection requirement. *See id* and page 6, paragraph 28, with reference to figure 1b.

In other embodiments, an air grate **100** may comprise one or more pieces of one or more materials adapted to partially cover a spanned area to allow air to flow through a plurality of

openings disposed in the uncovered portion of the spanned area to meet a semiconductor device manufacturing air flow requirement, with the one or more pieces of one or more materials being further adapted to cover the perimeter of the spanned area with an inwardly inclined edge 106 to meet a semiconductor device manufacturing spill protection requirement. *See* pages 4-5, paragraphs 13-18; page 5, paragraphs 19-20, with reference to figure 2; and page 6, paragraph 28, with reference to figure 1b.

Further, methods for making air grate 100 in accordance with embodiments of the present inventions could also comprise forming an air grate mold for use to make an air grate that meets one or more semiconductor manufacturing requirements. *See* pages 6-7, paragraph 30, with reference to figure 3, block 302. The semiconductor manufacturing requirements could be one or more of (a) a semiconductor device manufacturing spill protection requirement, (b) a semiconductor device manufacturing air flow requirement, (c) a semiconductor device manufacturing fall through object size limitation, and (d) a semiconductor device manufacturing weight fall requirement. *See id*; and pages 4-5, paragraphs 13-18. In various embodiments, methods for making air grate 100 in accordance with embodiments of the present inventions could further comprise injecting a material into the air grate mold to create an air grate. *See* page 7, paragraph 31, with reference to figure 3, block 304. In various embodiments, methods in accordance with this invention could further comprise removing air grate 100 from the mold. *See* page 7, paragraph 31, with reference to figure 3, block 306.

CONCLUSION

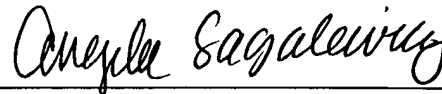
Appellant respectfully submits that this new summary of the claimed subject matter puts appellant's appeal brief into compliance with 37 C.F.R. §41.37 and requests that the Board of Patent Appeals and Interferences consider the arguments set forth in the previously-filed appeal brief to overrule the Examiner and direct allowance of the rejected claims.

Appellant previously submitted the appeal brief with a check for \$500 to cover the appeal fee for one other than a small entity as specified in 37 C.F.R. §1.17(c). We do not believe any fees, in particular extension of time fees, are needed with this submission. However, should fees be necessary, please charge Deposit Account No. 500393. In addition, please credit any overages to the same account.

Respectfully submitted,

SCHWABE, WILLIAMSON & WYATT, P.C.

Dated: 12-27-2005



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